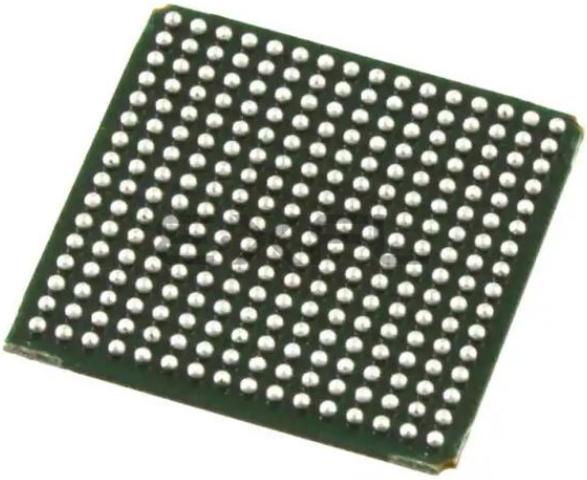


Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	1936
Total RAM Bits	94208
Number of I/O	160
Number of Gates	139000
Voltage - Supply	2.3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfx125eb-03fn256c

SELECT DEVICES DISCONTINUED

ispXPGA Family Overview

The ispXPGA family of devices provides the ideal vehicle for the creation of high-performance logic designs that are both non-volatile and infinitely re-programmable. Other FPGA solutions force a compromise, being either re-programmable or non-volatile. This family couples this capability with a mainstream architecture containing the features required for today's system-level design.

The ispXPGA family is available in two options. The standard device supports sysHSI capability for ultra fast serial communications while the lower-cost "E-Series" supports the same high-performance FPGA fabric without the sysHSI Block.

Electrically Erasable CMOS (E^2CMOS) memory cells provide the ispXPGA family with non-volatile capability. These allow logic to be functional microseconds after power is applied, allowing easy interfacing in many applications. This capability also means that expensive external configuration memories are not required and that designs can be secured from unauthorized read back. Internal SRAM cells allow the device to be infinitely reconfigured if desired. Both the SRAM and E^2CMOS cells can be programmed and verified through the IEEE 1532 industry standard. Additionally, the SRAM cells can be configured and read-back through the sysCONFIG™ peripheral port.

The family spans the density and I/O range required for the majority of today's logic designs, 139K to 1.25M functional gates and 160 to 496 I/O. The devices are available for operation from 1.8V, 2.5V, and 3.3V power supplies, providing easy integration into the overall system.

System-level design needs are met through the incorporation of sysMEM dual-port memory blocks, sysIO advanced I/O support, and sysCLOCK Phase Locked Loops (PLLs). High-speed serial communications are supported through multiple sysHSI blocks, which provide clock data recovery (CDR) and serialization/de-serialization (SERDES).

The ispLEVER™ design tool from Lattice allows easy implementation of designs using the ispXPGA product. Synthesis library support is available for major logic synthesis tools. The ispLEVER tool takes the output from these common synthesis packages and place and routes the design in the ispXPGA product. The tool supports floor planning and the management of other constraints within the device. The tool also provides outputs to common timing analysis tools for timing analysis.

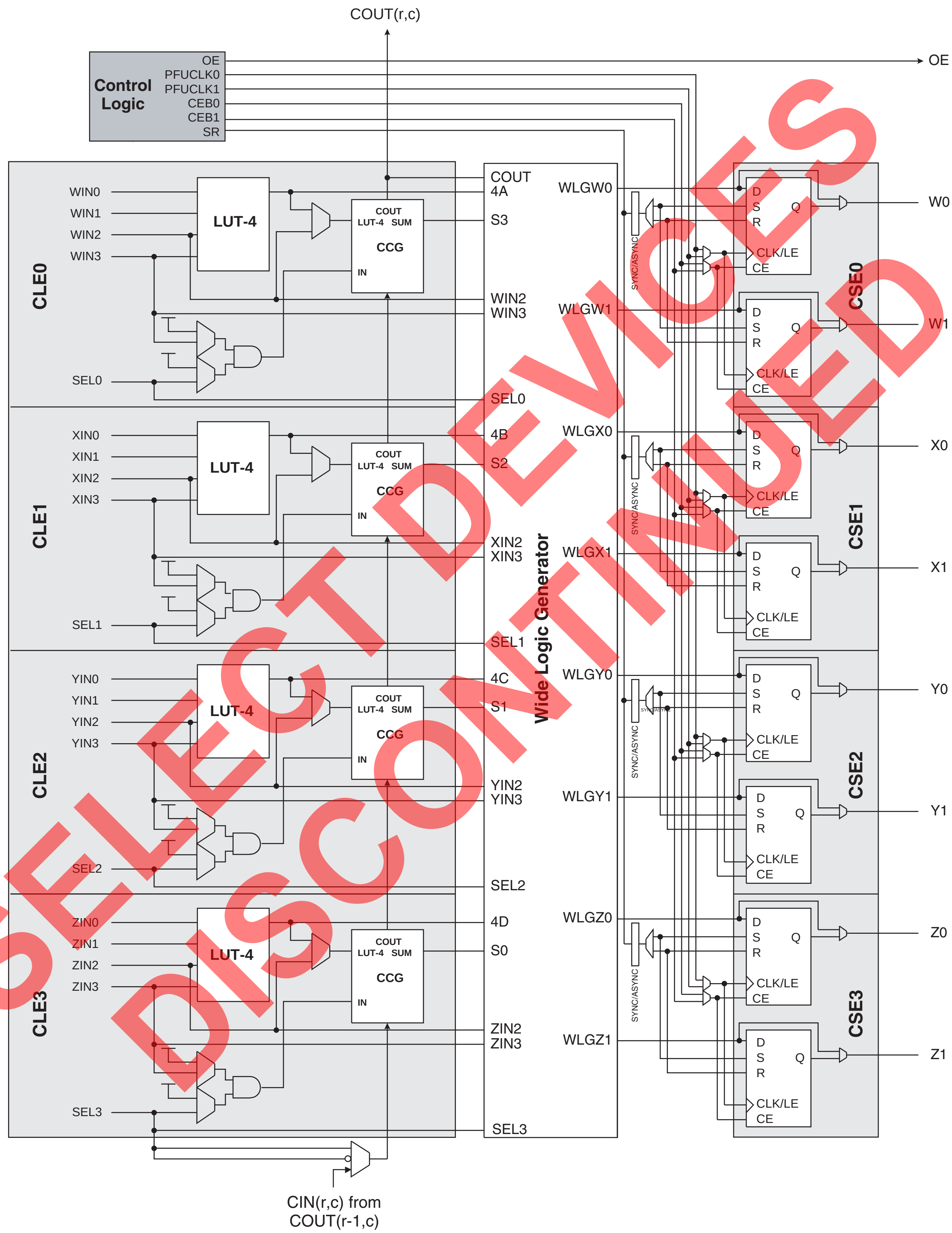
To increase designer productivity, Lattice provides a variety of pre-designed modules referred to as IP cores for the ispXPGA product. These IP cores allow designers to concentrate on the unique portions of their design while using pre-designed blocks to implement standard functions such as bus interfaces, standard communication interfaces, and memory controllers.

Through the use of advanced technology and innovative architecture the ispXPGA FPGA devices provide designers with excellent speed performance. Although design dependent, many typical designs can run at over 150MHz. Certain designs can run at over 300MHz. Table 2 details the performance of several building blocks commonly used by logic designers.

Table 2. ispXPGA Speed Performance for Typical Building Blocks

Function	Performance
8:1 Asynch MUX	150 MHz
1:32 Asynch Demultiplexer	125 MHz
8 x 8 2-LL Pipelined Multiplier	225 MHz
32-bit Up/Down Counter	290 MHz
32-bit Shift Register	360 MHz

Figure 2. ispXPGA PFU



SELECT DEVICES DISCONTINUED

Configurable Logic Element

The CLE is made up of a four-input Look-up Table (LUT-4), a Carry Chain Generator (CCG), and a two-input AND gate. The LUT-4 creates various combinatorial and memory elements, the CCG creates a single one-bit full adder, and the two-input AND gate can expand the CCG to incorporate Booth Multiplier capability by feeding the output of the AND gate to one of the inputs of the CCG.

Of the five inputs that feed each CLE, two are dedicated inputs into each LUT-4 and the remaining three take on varying functionality. The third and fourth inputs can be used as either inputs to the LUT-4 or as a Feed-Thru to the CSE via the WLG. The fifth input can be a data port when the LUT is configured as Distributed Memory, a select line for multiplexer operation, or a Feed-Thru directly to the CSE via the WLG (Figure 2).

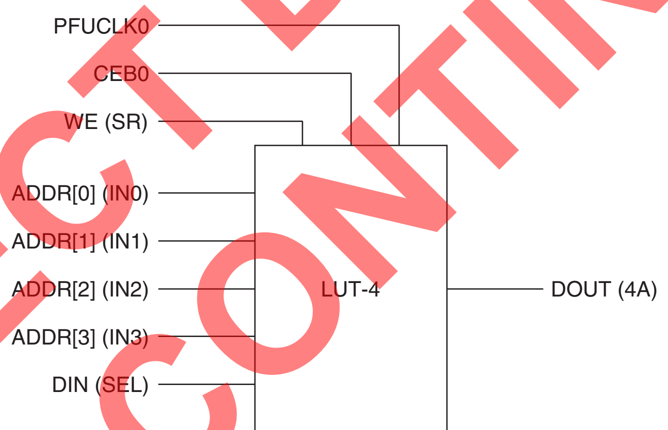
Look-Up Table – Combinatorial Mode

In combinatorial mode, the LUT-4 can implement any logic function up to four inputs. By using the carry chain and the WLG, each LUT-4 can be combined to form the enhanced functions listed in Table 3.

Look-Up Table – Distributed Memory Mode

In the distributed memory mode, the LUT functions as a memory element. The inputs to the LUT function as Address and Data. Each PFU is capable of implementing up to 64 SRAM bits. Both single and double port RAM can be performed in the PFU (Table 3). Furthermore, the distributed memory can be configured as either synchronous or asynchronous memory. Figure 3 illustrates the LUT while in distributed memory mode. When using any LUT in the PFU in memory mode, the Set/Reset signal will be used for Write Enable (WE(SR)) and the CLK0 signal will be used as the clock for synchronous read and write.

Figure 3. LUT in Distributed Memory Mode

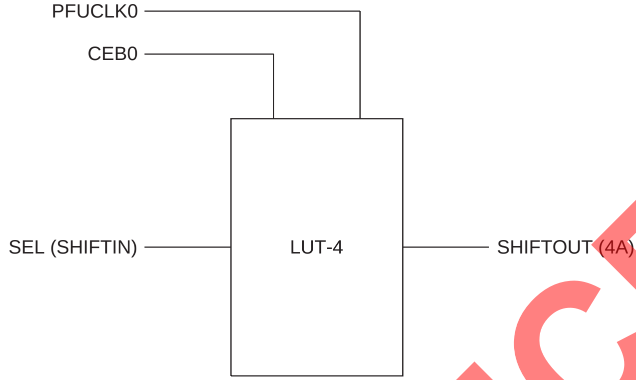


Look-Up Table – Shift Register Mode

In the shift register mode, the LUT functions as a 1-bit to 8-bit shift register. This means that each PFU can implement up to four 8-bit shift registers or any cascaded combination. Figure 4 illustrates the LUT when configured in shift register mode.

SELECT DEVICES DISCONTINUED

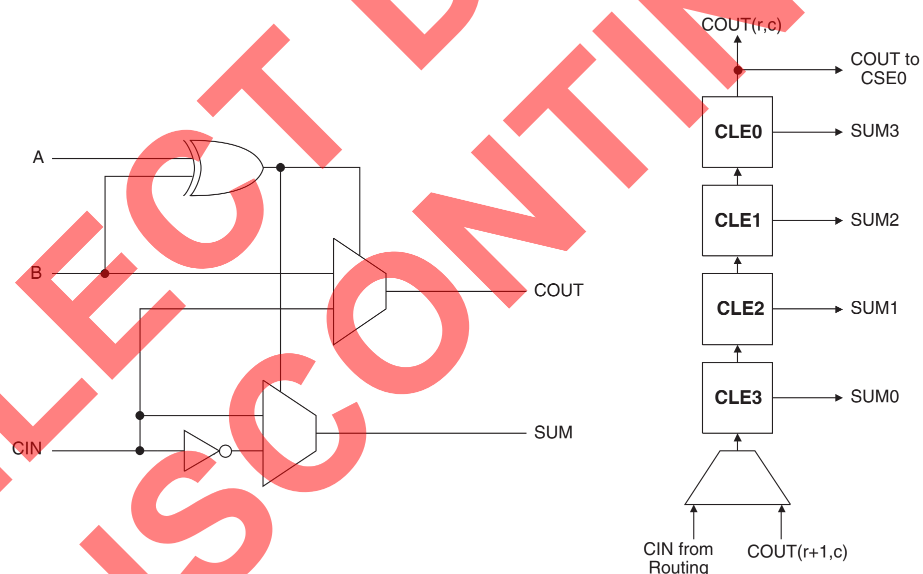
Figure 4. LUT in Shift Register Mode



Carry Chain Generator

The Carry Chain Generator is useful for implementing high-speed arithmetic functions. The CCG consists of a two-input XOR gate whose carryout can be cascaded with the input of the adjacent CCG. As shown in Figure 5, the carryin signal feeds CLE3 of the PFU and is propagated through CLE2 and CLE1 before reaching CLE0. The sum output of the CCG can be fed to the CSE through the WLG. The carryout must propagate to CLE0 for use outside the PFU. The carryout from the PFU can feed the W0 input of CSE0. The CCG also helps to effectively implement wider functions by using its logic elements to expand the capabilities of the LUT-4.

Figure 5. Carry Chain Generator



Wide Logic Generator

The WLG contains the logic necessary to implement wide gate functions. This is made up of a set of multiplexers that are located between the CLE and the CSE. The WLG helps in enhancing the wide gating capability of the PFU. The outputs of each CLE can be cascaded in the WLG to build wide gating functions. Wide multiplexing functions are also possible with a similar use of the WLG. Figure 6 illustrates the WLG.

SELECT DEVICES DISCONTINUED

Memory

The ispXPGA architecture provides a large amount of resources for memory intensive applications. Embedded Block RAMs (EBRs) are available to complement the Distributed Memory that is configured in the PFUs (see Look-Up Table -Distributed Memory Mode in the PFU section above). Each memory element can be configured as RAM or ROM. Additionally, the internal logic of the device can be used to configure the memory elements as FIFO and other storage types. These EBRs are referred to as sysMEM blocks. Refer to Table 1 for memory resources per device.

sysMEM Blocks

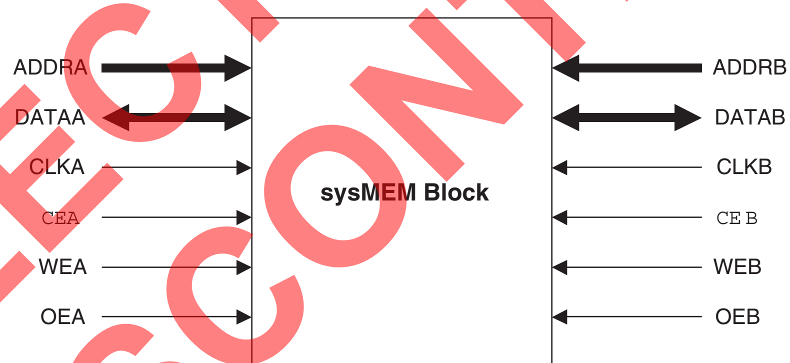
The sysMEM blocks are organized in columns distributed throughout the device. Each EBR contains 4.6K bits of dual-port RAM with dedicated control, address, and data lines for each port. Each column of sysMEM blocks has dedicated address and control lines that can be used by each block separately or cascaded to form larger memory elements. The memory cells are symmetrical and contain two sets of identical control signals. Each port has a read/write clock, clock enable, write enable, and output enable. Figure 12 illustrates the sysMEM block.

The ispXPGA memory block can operate as single-port or dual-port RAM. Supported configurations are:

- 512 x 9 bits single-port (8 bits data / 1 bit parity)
- 256 x 18 bits single-port (16 bits data / 2 bits parity)
- 512 x 9 bits dual-port (8 bits data / 1 bit parity)
- 256 x18 bits dual-port (16 bits data / 2 bits parity)

The data widths of “9” and “18” are ideal for applications where parity is necessary. This allows 9 data bits, 8 data bits plus a parity bit, 18 data bits, or 16 data bits plus two parity bits. The logic for generating and checking the parity must be customized separately.

Figure 12. sysMEM Block Diagram



Read and Write Operations

The ispXPGA EBR has fully synchronous read and write operations as well as an asynchronous read operation. These operations allow several different types of memory to be implemented in the device.

Synchronous Read: The Clock Enable ($\overline{CE}$) and Write Enable (WE) signals control the synchronous read operation. When the $\overline{CE}$ signal is low, the clock is enabled. When the WE signal is low the read operation begins. Once the address (ADDR) is present, a rising clock edge (or falling edge depending on polarity) causes the stored data to be available on the DATA port. Figure 13 illustrates the synchronous read timing.

SELECT DEVICES DISCONTINUED

Absolute Maximum Ratings[1, 2, 3]

	1.8V	2.5V/3.3V
Supply Voltage (V_{CC})	-0.5 to 2.5V	-0.5 to 5.5V
PLL Supply Voltage (V_{CCP})	-0.5 to 2.5V	-0.5 to 5.5V
Output Supply Voltage (V_{CCO})	-0.5 to 4.5V	-0.5 to 4.5V
IEEE 1149.1 TAP Supply Voltage (V_{CCJ})	-0.5 to 4.5V	-0.5 to 4.5V
Input Voltage Applied[4, 5]	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C
Junction Temperature (T_J) with Power Applied	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied (while programming, following the programming specifications).
2. Compliance with the Lattice Thermal Management document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to (V_{IH} (MAX) + 2) volts not to exceed 6V is permitted for a duration of <20ns.
5. A maximum of 64 I/Os per device with V_{IN} > 3.6V is allowed.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
V_{CC}	Supply Voltage for 1.8V device[1]	1.65	1.95	V
	Supply Voltage for 2.5V device	2.3	2.7	V
	Supply Voltage for 3.3V device	3.0	3.6	V
V_{CCP}	Supply Voltage for PLL and sysHSI blocks, 1.8V devices[1]	1.65	1.95	V
	Supply Voltage for PLL and sysHSI blocks, 2.5V devices	2.3	2.7	V
	Supply Voltage for PLL and sysHSI blocks, 3.3V devices	3.0	3.6	V
V_{CCJ}	Supply Voltage for IEEE 1149.1 Test Access Port for LVCMOS 1.8V	1.65	1.95	V
	Supply Voltage for IEEE 1149.1 Test Access Port for LVCMOS 2.5V	2.3	2.7	V
	Supply Voltage for IEEE 1149.1 Test Access Port for LVCMOS 3.3V	3.0	3.6	V
T_J (COM)	Junction Temperature Commercial Operation	0	85	C
T_J (IND)	Junction Temperature Industrial Operation	-40	105	C

1. sysHSI specification is valid for V_{CC} and V_{CCP} = 1.7V to 1.9V.

E^2CMOS Erase Reprogram Specifications

Parameter	Min	Max	Units
Erase/Reprogram Cycle[1]	1,000	—	Cycles

1. Valid over commercial temperature range.

Hot Socketing Characteristics[1, 2, 3, 4]

Symbol	Parameter	Condition	Min	Typ	Max	Units
I_{DK}	Input or Tristated I/O Leakage Current	0 ð V_{IN} ð 3.0V	—	+/-50	+/-800	µA

1. Insensitive to sequence of V_{CC} and V_{CCO} when V_{CCO} ð 1.0V. For V_{CCO} > 1.0V, V_{CC} min must be present. However, assumes monotonic rise/fall rates for V_{CC} and V_{CCO}, provided (V_{IN} - V_{CCO}) ð 3.6V.
2. LVTTL, LVCMOS only.
3. 0 < V_{CC} ð V_{CC} (MAX), 0 < V_{CCO} ð V_{CCO} (MAX).
4. I_{DK} is additive to I_{PU}, I_{PD} or I_{BH}. Device defaults to pull-up until non-volatile cells are active.

SELECT DEVICES DISCONTINUED

sysIO Recommended Operating Conditions

Standard	V_{CCO} (V)[1]			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3	3.0	3.3	3.6	-	-	-
LVCMOS 2.5	2.3	2.5	2.7	-	-	-
LVCMOS 1.8[2]	1.65	1.8	1.95	-	-	-
LVTTL	3.0	3.3	3.6	-	-	-
PCI 3.3	3.0	3.3	3.6	-	-	-
AGP-1X	3.15	3.3	3.45	-	-	-
SSTL 2	2.3	2.5	2.7	1.15	1.25	1.35
SSTL 3	3.0	3.3	3.6	1.3	1.5	1.7
CTT 3.3	3.0	3.3	3.6	1.35	1.5	1.65
CTT 2.5	2.3	2.5	2.7	1.35	1.5	1.65
HSTL Class I	1.4	1.5	1.6	0.68	0.75	0.9
HSTL Class III	1.4	1.5	1.6	-	0.9	-
GTL+	-	-	-	0.882	1.0	1.122
LVDS	2.3	2.5	2.7	-	-	-
LVPECL	3.0	3.3	3.6	-	-	-
BLVDS	2.3	2.5	2.7	-	-	-

1. Inputs independent of V_{CCO}.
2. Design tool default setting.

SELECT DEVICES DISCONTINUED

ispXPGA 125B/C & ispXPGA 125EB/EC Timing Adders (Cont.)

Parameter	Description	Base Parameter	-5[1]		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
LVCMOS_33_4mA_out	Using 3.3V CMOS Standard, 4mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
LVCMOS_33_5.33mA_out	Using 3.3V CMOS Standard, 5.33mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
LVCMOS_33_8mA_out	Using 3.3V CMOS Standard, 8mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.7	—	0.7	—	0.7	ns
LVCMOS_33_12mA_out	Using 3.3V CMOS Standard, 12mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
LVCMOS_33_16mA_out	Using 3.3V CMOS Standard, 16mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
LVCMOS_33_24mA_out	Using 3.3V CMOS Standard, 24mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
AGP_1X_out	Using AGP 1x Standard	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
CTT25_out	Using CTT 2.5V	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
CTT33_out	Using CTT 3.3V	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
GTL+_out	Using GTL+	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
HSTL_I_out	Using HSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
HSTL_III_out	Using HSTL 2.5V, Class III	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
LVDS_out	Using Low Voltage Differential Signaling (LVDS)	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
BLVDS_out	Using Bus Low Voltage Differential Signaling (BLVDS)	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
LVPECL_out	Using Low Voltage PECL	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
PCI_out	Using PCI Standard	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL2_I_out	Using SSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL2_II_out	Using SSTL 2.5V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL3_I_out	Using SSTL 3.3V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL3_II_out	Using SSTL 3.3V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns

1. Only available for ispXPGA 125B and ispXPGA 125EB (2.5V/3.3V) devices.

Timing v.0.3

SELECT DEVICES DISCONTINUED

ispXPGA 200B/C & ispXPGA 200EB/EC PFU Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-5[1]		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Reset/Set								
t_{LASSRO}	Asynchronous Set/Reset to Output	—	1.09	—	1.17	—	1.35	ns
$t_{LASSRPW}$	Asynchronous Set/Reset Pulse Width	4.19	—	4.50	—	5.18	—	ns
t_{LASSRR}	Asynchronous Set/Reset Recovery	—	0.51	—	0.55	—	0.63	ns
t_{LSSR_S}	Synchronous Set/Reset Setup Time	-0.03	—	-0.03	—	-0.03	—	ns
t_{LSSR_H}	Synchronous Set/Reset Hold Time	0.03	—	0.03	—	0.03	—	ns

1. Only available for ispXPGA 200B and ispXPGA 200EB (2.5V/3.3V) devices.
2. $t_{LCTHRUL}$ quoted bit by bit.

Timing v.0.3

ispXPGA 200B/C & ispXPGA 200EB/EC PIC Timing Parameters

Parameter	Description	-5[1]		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Register/Latch Delays								
t_{IO_CO}	Register Clock to Output Delay	—	0.93	—	1.00	—	1.15	ns
t_{IO_S}	Register Setup Time (Data before Clock)	0.05	—	0.05	—	0.06	—	ns
t_{IO_H}	Register Hold Time (Data after Clock)	0.06	—	0.06	—	0.07	—	ns
t_{IOCE_S}	Register Clock Enable Setup Time	-0.03	—	-0.03	—	-0.03	—	ns
t_{IOCE_H}	Register Clock Enable Hold Time	0.13	—	0.13	—	0.15	—	ns
t_{IO_GO}	Latch Gate to Output Delay	—	0.72	—	0.77	—	0.89	ns
t_{IOL_S}	Latch Setup Time	0.05	—	0.05	—	0.06	—	ns
t_{IOL_H}	Latch Hold Time	0.06	—	0.06	—	0.07	—	ns
t_{IOLPD}	Latch Propagation Delay (Transparent Mode)	—	0.09	—	0.10	—	0.12	ns
t_{IOASRO}	Asynchronous Set/Reset to Output	—	1.04	—	1.12	—	1.29	ns
$t_{IOASRPW}$	Asynchronous Set/Reset Pulse Width	4.19	—	4.50	—	5.18	—	ns
t_{IOASRR}	Asynchronous Set/Reset Recovery Time	—	0.23	—	0.25	—	0.29	ns
Input/Output Delays								
t_{IOBUF}	Output Buffer Delay	—	0.97	—	1.04	—	1.20	ns
t_{IOIN}	Input Buffer Delay	—	0.60	—	0.64	—	0.74	ns
t_{IOEN}	Output Enable Delay	—	0.53	—	0.57	—	0.66	ns
t_{IODIS}	Output Disable Delay	—	-0.13	—	-0.12	—	-0.10	ns
t_{IOFT}	Feed-thru Delay	—	0.19	—	0.20	—	0.23	ns

1. Only available for ispXPGA 200B and ispXPGA 200EB (2.5V/3.3V) devices.

Timing v.0.3

SELECT DEVICES DISCONTINUED

ispXPGA 500B/C & ispXPGA 500EB/EC External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Conditions	-5[1]		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{CO}	Global Clock Input to Output	PIO Output Register	—	6.4	—	6.9	—	7.9	ns
t_S	Global Clock Input Setup	PIO Input Register without input delay	-2.9	—	-2.7	—	-2.3	—	ns
t_H	Global Clock Input Hold	PIO Input Register without input delay	3.6	—	3.9	—	4.5	—	ns
t_{SINDLY}	Global Clock Input Setup	PIO Input Register with input delay	3.3	—	3.6	—	4.1	—	ns
t_{HINDLY}	Global Clock Input Hold	PIO Input Register with input delay	0.0	—	0.0	—	0.0	—	
t_{COPLL}	Global Clock Input to Output	PIO Output Register using PLL without delay	—	3.2	—	3.4	—	3.9	ns
t_{SPLL}	Global Clock Input Setup	PIO Input Register without input delay using PLL without delay	0.1	—	0.2	—	0.3	—	ns
t_{HPLL}	Global Clock Input Hold	PIO Input Register without input delay using PLL without delay	0.8	—	0.9	—	1.0	—	ns
$t_{SINDLYPLL}$	Global Clock Input Setup	PIO Input Register with input delay using PLL without delay	6.7	—	7.2	—	8.3	—	ns
$t_{HINDLYPLL}$	Global Clock Input Hold	PIO Input Register with input delay using PLL without delay	-4.3	—	-4.0	—	-3.4	—	ns

1. Only available for ispXPGA 500B and ispXPGA 500EB (2.5V/3.3V) devices.

Timing v.0.3

SELECT DEVICES DISCONTINUED

ispXPGA 1200B/C & ispXPGA 1200EB/EC External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Conditions	-5[1]		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{CO}	Global Clock Input to Output	PIO Output Register	—	6.6	—	7.1	—	8.2	ns
t_S	Global Clock Input Setup	PIO Input Register without input delay	-2.7	—	-2.7	—	-2.3	—	ns
t_H	Global Clock Input Hold	PIO Input Register without input delay	4.5	—	4.6	—	5.3	—	ns
t_{SINDLY}	Global Clock Input Setup	PIO Input Register with input delay	3.8	—	3.8	—	4.4	—	ns
t_{HINDLY}	Global Clock Input Hold	PIO Input Register with input delay	0.0	—	0.0	—	0.0	—	
t_{COPLL}	Global Clock Input to Output	PIO Output Register using PLL without delay	—	3.1	—	3.3	—	3.8	ns
t_{SPLL}	Global Clock Input Setup	PIO Input Register without input delay using PLL without delay	0.5	—	0.5	—	0.6	—	ns
t_{HPLL}	Global Clock Input Hold	PIO Input Register without input delay using PLL without delay	0.8	—	0.8	—	1.0	—	ns
$t_{SINDLYPLL}$	Global Clock Input Setup	PIO Input Register with input delay using PLL without delay	7.6	—	7.6	—	8.8	—	ns
$t_{HINDLYPLL}$	Global Clock Input Hold	PIO Input Register with input delay using PLL without delay	-4.1	—	-4.0	—	-3.4	—	ns

1. Only available for ispXPGA 1200B and ispXPGA 1200EB (2.5V/3.3V) devices.

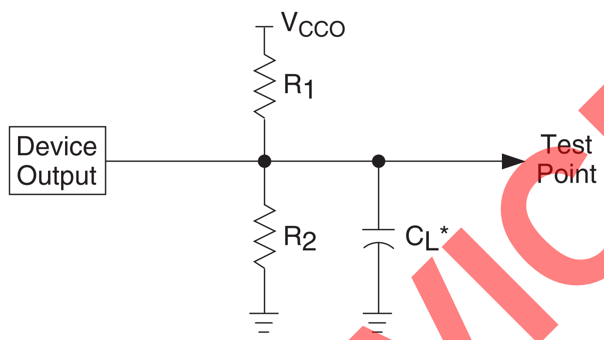
Timing v.0.2

SELECT DEVICES DISCONTINUED

Switching Test Conditions

Figure 25 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 7.

Figure 25. Output Test Load, LVTTL and LVCMOS Standards



*C_L includes test fixture and probe capacitance.

Table 7. Text Fixture Required Components

Test Condition	R_1	R_2	C_L	Timing Reference	VCCO
LVCMOS I/O, (L -> H, H -> L)	106	106	35pF	LVCMOS 3.3 = V_{CCO}/2	LVCMOS 3.3 = 3.0V
				LVCMOS 2.5 = V_{CCO}/2	LVCMOS 2.5 = 2.3V
				LVCMOS 1.8 = V_{CCO}/2	LVCMOS 1.8 = 1.65V
Default LVCMOS 1.8 I/O (Z -> H)	×	106	35pF	0.9V	1.65V
Default LVCMOS 1.8 I/O (Z -> L)	106	×	35pF	0.9V	1.65V
Default LVCMOS 1.8 I/O (H -> Z)	×	106	5pF	V_{OH} - 0.3	1.65V
Default LVCMOS 1.8 I/O (L -> Z)	106	×	5pF	V_{OL} + 0.3	1.65V

Note: Output test conditions for all other interfaces are determined by the respective standards.

SELECT DEVICES DISCONTINUED

ispXPGA Logic Signal Connections: 256-Ball fpBGA (Cont.)

256-fpBGA Ball	LFX200			LFX125		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[2]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[2]
-	GND (Bank 2)	-	-	GND (Bank 2)	-	-
R8	BK2_IO19	-	35N	BK2_IO19	-	31N
N8	BK2_IO20	-	36P	BK2_IO20	-	32P
P8	BK2_IO21	-	36N	BK2_IO21	-	32N
-	GND (Bank 2)	-	-	-	-	-
-	GND (Bank 3)	-	-	-	-	-
T8	BK3_IO0	-	39P	BK3_IO0	-	33P
T9	BK3_IO1	-	39N	BK3_IO1	-	33N
R9	BK3_IO2	-	40P	BK3_IO2	-	34P
-	-	-	-	GND (Bank 3)	-	-
R10	BK3_IO3	-	40N	BK3_IO3	-	34N
P9	BK3_IO4	-	41P	BK3_IO4	-	35P
N9	BK3_IO5	-	41N	BK3_IO5	-	35N
T10	BK3_IO6	-	42P	BK3_IO6	-	36P
-	GND (Bank 3)	-	-	-	-	-
T11	BK3_IO7	-	42N	BK3_IO7	-	36N
P10	BK3_IO8	-	43P	BK3_IO8	-	37P
-	-	-	-	GND (Bank 3)	-	-
N10	BK3_IO9	-	43N	BK3_IO9	-	37N
R11	BK3_IO14	-	46P	BK3_IO10	-	38P
-	GND (Bank 3)	-	-	-	-	-
R12	BK3_IO15	-	46N	BK3_IO11	-	38N
P11	BK3_IO16	VREF3	47P	BK3_IO12	VREF3	39P
N11	BK3_IO17	-	47N	BK3_IO13	-	39N
T12	BK3_IO18	-	48P	BK3_IO14	-	40P
T13	BK3_IO19	-	48N	BK3_IO15	-	40N
R13	BK3_IO20	-	49P	BK3_IO16	-	41P
-	-	-	-	GND (Bank 3)	-	-
R14	BK3_IO21	-	49N	BK3_IO17	-	41N
P12	BK3_IO22	-	50P	BK3_IO18	-	42P
-	GND (Bank 3)	-	-	-	-	-
N12	BK3_IO23	-	50N	BK3_IO19	-	42N
T14	GSR	-	-	GSR	-	-
T15	DXP	-	-	DXP	-	-
P13	DXN	-	-	DXN	-	-
P15	BK4_IO0	-	52P/HSI2	BK4_IO0	-	44P
N14	BK4_IO1	-	52N/HSI2	BK4_IO1	-	44N
R16	BK4_IO2	HSI2A_SINP	53P/HSI2	BK4_IO2	-	45P
-	GND (Bank 4)	-	-	-	-	-
P16	BK4_IO3	HSI2A_SINN	53N/HSI2	BK4_IO3	-	45N
N15	BK4_IO4	-	54P/HSI2	BK4_IO4	-	46P
-	-	-	-	GND (Bank 4)	-	-

SELECT DEVICES DISCONTINUED

ispXPGA Logic Signal Connections: 256-Ball fpBGA (Cont.)

256-fpBGA Ball	LFX200 Signal Name	LFX200 Second Function	LFX200 LVDS Pair/ sysHSI Reserved[2]	LFX125 Signal Name	LFX125 Second Function	LFX125 LVDS Pair/ sysHSI Reserved[2]
M15	BK4_IO5	-	54N/HSI2	BK4_IO5	-	46N
M14	BK4_IO8	-	56P/HSI2	BK4_IO6	-	47P
M13	BK4_IO9	VREF4	56N/HSI2	BK4_IO7	VREF4	47N
-	GND (Bank 4)	-	-	-	-	-
L13	BK4_IO12	PLL_RST4	58P/HSI2	BK4_IO8	PLL_RST4	48P
L14	BK4_IO13	PLL_RST5	58N/HSI2	BK4_IO9	PLL_RST5	48N
N16	BK4_IO14	HSI2B_SOUTP	59P/HSI2	BK4_IO10	-	49P
M16	BK4_IO15	HSI2B_SOUTN	59N/HSI2	BK4_IO11	-	49N
-	-	-	-	GND (Bank 4)	-	-
L15	BK4_IO18	SS_CLKIN1P	61P	BK4_IO14	SS_CLKIN1P	51P
-	GND (Bank 4)	-	-	-	-	-
K15	BK4_IO19	SS_CLKIN1N	61N	BK4_IO15	SS_CLKIN1N	51N
K14	BK4_IO20	PLL_FBK4	62P	BK4_IO16	PLL_FBK4	52P
K13	BK4_IO21	PLL_FBK5	62N	BK4_IO17	PLL_FBK5	52N
L16	BK4_IO22	SS_CLKOUT1P	63P	BK4_IO18	SS_CLKOUT1P	53P
-	-	-	-	GND (Bank 4)	-	-
K16	BK4_IO23	SS_CLKOUT1N	63N	BK4_IO19	SS_CLKOUT1N	53N
J13	BK4_IO24	CLK_OUT4	64P	BK4_IO20	CLK_OUT4	54P
J12	BK4_IO25	CLK_OUT5	64N	BK4_IO21	CLK_OUT5	54N
-	GND (Bank 4)	-	-	-	-	-
J14	GCLK4	-	LVDS Pair2P	GCLK4	-	LVDS Pair2P
H14	GCLK5	-	LVDS Pair2N	GCLK5	-	LVDS Pair2N
J15	VCCP1	-	-	VCCP1	-	-
H15	GNDP1	-	-	GNDP1	-	-
J16	GCLK6	-	LVDS Pair3P	GCLK6	-	LVDS Pair3P
H16	GCLK7	-	LVDS Pair3N	GCLK7	-	LVDS Pair3N
-	GND (Bank 5)	-	-	-	-	-
H12	BK5_IO0	CLK_OUT6	65P	BK5_IO0	CLK_OUT6	55P
H13	BK5_IO1	CLK_OUT7	65N	BK5_IO1	CLK_OUT7	55N
G14	BK5_IO2	-	66P	BK5_IO2	-	56P
-	-	-	-	GND (Bank 5)	-	-
G15	BK5_IO3	PLL_RST7	66N	BK5_IO3	PLL_RST7	56N
G13	BK5_IO6	PLL_RST6	68P	BK5_IO6	PLL_RST6	58P/HSI1
-	GND (Bank 5)	-	-	-	-	-
F13	BK5_IO7	PLL_FBK7	68N	BK5_IO7	PLL_FBK7	58N/HSI1
G16	BK5_IO10	HSI3A_SINP	70P	BK5_IO8	HSI1A_SINP	59P/HSI1
-	-	-	-	GND (Bank 5)	-	-
F16	BK5_IO11	HSI3A_SINN	70N/HSI3	BK5_IO9	HSI1A-SINN	59N/HSI1
F14	BK5_IO12	-	71P/HSI3	BK5_IO10	-	60P/HSI1
F15	BK5_IO13	-	71N/HSI3	BK5_IO11	-	60N/HSI1
E16	BK5_IO14	HSI3A_SOUTP	72P/HSI3	BK5_IO12	HSI1A_SOUTP	61P/HSI1
-	GND (Bank 5)	-	-	-	-	-

SELECT DEVICES DISCONTINUED

ispXPGA Logic Signal Connections: 516-Ball fpBGA (Cont.)

SELECT DEVICES DISCONTINUED

	LFX500			LFX200			LFX125		
516-Ball BGA Ball	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
AE3	BK1_IO33	-	37N/HSI2	NC	-	-	NC	-	-
AG1	BK1_IO34	-	38P/HSI2	NC	-	-	NC	-	-
AH1	BK1_IO35	-	38N/HSI2	NC	-	-	NC	-	-
AG2	BK1_IO36	-	39P/HSI2	NC	-	-	NC	-	-
AF3	BK1_IO37	-	39N/HSI2	NC	-	-	NC	-	-
AJ1	BK1_IO38	-	40P/HSI2	NC	-	-	NC	-	-
-	GND (Bank 1)	-	-	-	-	-	-	-	-
AH2	BK1_IO39	-	40N/HSI2	NC	-	-	NC	-	-
AG3	BK1_IO40	-	41P	BK1_IO24	-	25P/HSI1	NC	-	-
AF4	BK1_IO41	-	41N	BK1_IO25	-	25N/HSI1	NC	-	-
AK2	TCK	-	-	TCK	-	-	TCK	-	-
AJ3	TMS	-	-	TMS	-	-	TMS	-	-
AG5	TOE	-	-	TOE	-	-	TOE	-	-
AH4	BK2_IO0	-	42P	BK2_IO0	-	26P	BK2_IO0	-	22P
AK3	BK2_IO1	-	42N	BK2_IO1	-	26N	BK2_IO1	-	22N
AJ4	BK2_IO2	-	43P	BK2_IO2	-	27P	BK2_IO2	-	23P
-	GND (Bank 2)	-	-	GND (Bank 2)	-	-	-	-	-
AH5	BK2_IO3	-	43N	BK2_IO3	-	27N	BK2_IO3	-	23N
AK4	BK2_IO4	-	44P	BK2_IO4	-	28P	BK2_IO4	-	24P
-	-	-	-	-	-	-	GND (Bank 2)	-	-
AJ5	BK2_IO5	-	44N	BK2_IO5	-	28N	BK2_IO5	-	24N
AG7	BK2_IO6	-	45P	BK2_IO6	-	29P	BK2_IO6	-	25P
AH6	BK2_IO7	-	45N	BK2_IO7	-	29N	BK2_IO7	-	25N
AK5	BK2_IO8	-	46P	NC	-	-	NC	-	-
AJ6	BK2_IO9	-	46N	NC	-	-	NC	-	-
AG8	BK2_IO10	-	47P	NC	-	-	NC	-	-
-	GND (Bank 2)	-	-	-	-	-	-	-	-
AH7	BK2_IO11	-	47N	NC	-	-	NC	-	-
AK6	BK2_IO12	-	48P	NC	-	-	NC	-	-
AJ7	BK2_IO13	-	48N	NC	-	-	NC	-	-
AH8	BK2_IO14	-	49P	NC	-	-	NC	-	-
AG10	BK2_IO15	-	49N	NC	-	-	NC	-	-
AK7	BK2_IO16	-	50P	NC	-	-	NC	-	-
AJ8	BK2_IO17	-	50N	NC	-	-	NC	-	-
AH9	BK2_IO18	-	51P	NC	-	-	NC	-	-
-	GND (Bank 2)	-	-	-	-	-	-	-	-
AG11	BK2_IO19	-	51N	NC	-	-	NC	-	-
AK8	BK2_IO20	-	52P	BK2_IO8	-	30P	BK2_IO8	-	26P
AJ9	BK2_IO21	VREF2	52N	BK2_IO9	VREF2	30N	BK2_IO9	VREF2	26N
AH10	BK2_IO22	-	53P	BK2_IO10	-	31P	BK2_IO10	-	27P
-	-	-	-	GND (Bank 2)	-	-	-	-	-
AH11	BK2_IO23	-	53N	BK2_IO11	-	31N	BK2_IO11	-	27N
AJ10	BK2_IO24	-	54P	BK2_IO12		32P	BK2_IO12	-	28P
AK10	BK2_IO25	-	54N	BK2_IO13	-	32N	BK2_IO13	-	28N
AH12	BK2_IO26	-	55P	BK2_IO14	-	33P	BK2_IO14	-	29P
-	GND (Bank 2)	-	-	-	-	-	-	-	-
AJ11	BK2_IO27	-	55N	BK2_IO15	-	33N	BK2_IO15	-	29N
AK11	BK2_IO28	-	56P	NC	-	-	NC	-	-
AJ12	BK2_IO29	-	56N	NC	-	-	NC	-	-
AG13	BK2_IO30	-	57P	BK2_IO16	-	34P	BK2_IO16	-	30P
AH13	BK2_IO31	-	57N	BK2_IO17	-	34N	BK2_IO17	-	30N

ispXPGA Logic Signal Connections: 680-Ball fpBGA (Cont.)

LFX1200			
680-Ball fpBGA	Signal Name	Second Function	LVDS Pair/sysHSI Reserved[1]
-	GND (Bank 4)	-	-
AW26	BK4_IO43	-	145N
AV25	BK4_IO44	-	146P
AT24	BK4_IO45	-	146N
AU24	BK4_IO46	-	147P
AU25	BK4_IO47	-	147N
AW25	BK4_IO48	PLL_RST4	148P
AW24	BK4_IO49	PLL_RST5	148N
AU23	BK4_IO50	-	149P
-	GND (Bank 4)	-	-
AT23	BK4_IO51	-	149N
AV24	BK4_IO52	-	150P
AW23	BK4_IO53	-	150N
AV23	BK4_IO54	SS_CLKIN1P	151P
AU22	BK4_IO55	SS_CLKIN1N	151N
AR21	BK4_IO56	PLL_FBK4	152P
AT22	BK4_IO57	PLL_FBK5	152N
AV22	BK4_IO58	SS_CLKOUT1P	153P
-	GND (Bank 4)	-	-
AV21	BK4_IO59	SS_CLKOUT1N	153N
AT21	BK4_IO60	CLK_OUT4	154P
AU21	BK4_IO61	CLK_OUT5	154N
-	GND (Bank 4)	-	-
AT19	GCLK4	-	LVDS Pair2P
AU19	GCLK5	-	LVDS Pair2N
AW22	VCCP1	-	-
AR20	GNDP1	-	-
AU18	GCLK6	-	LVDS Pair3P
AT18	GCLK7	-	LVDS Pair3N
-	GND (Bank 5)	-	-
AV17	BK5_IO0	CLK_OUT6	155P
AV18	BK5_IO1	CLK_OUT7	155N
AW21	BK5_IO2	PLL_FBK6	156P
-	GND (Bank 5)	-	-
AV19	BK5_IO3	PLL_FBK7	156N
AR19	BK5_IO4	-	157P/HSI7
AW19	BK5_IO5	-	157N/HSI7
AW18	BK5_IO6	PLL_RST6	158P/HSI7
AW17	BK5_IO7	PLL_RST7	158N/HSI7
AT17	BK5_IO8	-	159P/HSI7
AV16	BK5_IO9	-	159N/HSI7
AU17	BK5_IO10	HSI7A_SINP	160P/HSI7
-	GND (Bank 5)	-	-

SELECT DEVICES DISCONTINUED

ispXPGA Logic Signal Connections: 680-Ball fpBGA (Cont.)

LFX1200			
680-Ball fpBGA	Signal Name	Second Function	LVDS Pair/sysHSI Reserved[1]
AT16	BK5_IO11	HSI7A_SINN	160N/HSI7
AW16	BK5_IO12	-	161P/HSI7
AU16	BK5_IO13	-	161N/HSI7
AV14	BK5_IO14	HSI7A_SOUTP	162P/HSI7
AV15	BK5_IO15	HSI7A_SOUTN	162N/HSI7
AU15	BK5_IO16	-	163P/HSI7
AW15	BK5_IO17	-	163N/HSI7
AT15	BK5_IO18	HSI7B_SINP	164P/HSI7
-	GND (Bank 5)	-	-
AR16	BK5_IO19	HSI7B_SINN	164N/HSI7
AW14	BK5_IO20	-	165P/HSI8
AW13	BK5_IO21	-	165N/HSI8
AR14	BK5_IO22	HSI7B_SOUTP	166P/HSI8
AT14	BK5_IO23	HSI7B_SOUTN	166N/HSI8
AT13	BK5_IO24	-	167P/HSI8
AV13	BK5_IO25	-	167N/HSI8
AU12	BK5_IO26	HSI8A_SINP	168P/HSI8
-	GND (Bank 5)	-	-
AU13	BK5_IO27	HSI8A_SINN	168N/HSI8
AV12	BK5_IO28	-	169P/HSI8
AT12	BK5_IO29	-	169N/HSI8
AR12	BK5_IO30	HSI8A_SOUTP	170P/HSI8
AT11	BK5_IO31	HSI8A_SOUTN	170N/HSI8
AW12	BK5_IO32	-	171P/HSI8
AU11	BK5_IO33	-	171N/HSI8
AV9	BK5_IO34	HSI8B_SINP	172P/HSI8
-	GND (Bank 5)	-	-
AV10	BK5_IO35	HSI8B_SINN	172N/HSI8
AW10	BK5_IO36	-	173P/HSI9
AW9	BK5_IO37	-	173N/HSI9
AT10	BK5_IO38	HSI8B_SOUTP	174P/HSI9
AU9	BK5_IO39	HSI8B_SOUTN	174N/HSI9
AT9	BK5_IO40	-	175P/HSI9
AR10	BK5_IO41	-	175N/HSI9
AU8	BK5_IO42	HSI9A_SINP	176P/HSI9
-	GND (Bank 5)	-	-
AV8	BK5_IO43	HSI9A_SINN	176N/HSI9
AW8	BK5_IO44	-	177P/HSI9
AW7	BK5_IO45	-	177N/HSI9
AU7	BK5_IO46	HSI9A_SOUTP	178P/HSI9
AT8	BK5_IO47	HSI9A_SOUTN	178N/HSI9
AV7	BK5_IO48	-	179P/HSI9
AW6	BK5_IO49	VREF5	179N/HSI9

SELECT DEVICES DISCONTINUED

ispXPGA Logic Signal Connections: 900-Ball fpBGA (Cont.)

900 fpBGA Ball	LFX1200			LFX500		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
AK5	BK2_IO7	-	65N	BK2_IO7	-	45N
AE7	BK2_IO8	-	66P	BK2_IO8	-	46P
AF7	BK2_IO9	-	66N	BK2_IO9	-	46N
AG7	BK2_IO10	-	67P	BK2_IO10	-	47P
-	GND (Bank 2)	-	-	GND (Bank 2)	-	-
AH7	BK2_IO11	-	67N	BK2_IO11	-	47N
AE8	BK2_IO12	VREF2	68P	BK2_IO21	VREF2	52N
AF8	BK2_IO13	-	68N	BK2_IO20	-	52P
AJ6	BK2_IO14	-	69P	BK2_IO12	-	48P
AK6	BK2_IO15	-	69N	BK2_IO13	-	48N
AG8	BK2_IO16	-	70P	BK2_IO14	-	49P
AH8	BK2_IO17	-	70N	BK2_IO15	-	49N
AJ7	BK2_IO18	-	71P	BK2_IO16	-	50P
-	GND (Bank 2)	-	-	-	-	-
AK7	BK2_IO19	-	71N	BK2_IO17	-	50N
AF9	BK2_IO20	-	72P	BK2_IO18	-	51P
-	-	-	-	GND (Bank 2)	-	-
AG9	BK2_IO21	-	72N	BK2_IO19	-	51N
AJ8	BK2_IO22	-	73P	NC	-	-
AK8	BK2_IO23	-	73N	NC	-	-
AD10	BK2_IO24	-	74P	NC	-	-
AE10	BK2_IO25	-	74N	NC	-	-
AJ9	BK2_IO26	-	75P	NC	-	-
-	GND (Bank 2)	-	-	-	-	-
AK9	BK2_IO27	-	75N	NC	-	-
AF10	BK2_IO28	-	76P	NC	-	-
AG10	BK2_IO29	-	76N	NC	-	-
AK10	BK2_IO30	-	77P	NC	-	-
AJ10	BK2_IO31	-	77N	NC	-	-
AE11	BK2_IO32	-	78P	NC	-	-
AF11	BK2_IO33	-	78N	NC	-	-
AG11	BK2_IO34	-	79P	NC	-	-
-	GND (Bank 2)	-	-	-	-	-
AH11	BK2_IO35	-	79N	NC	-	-
AE12	BK2_IO36	-	80P	NC	-	-
AF12	BK2_IO37	-	80N	NC	-	-
AJ11	BK2_IO38	-	81P	NC	-	-
AK11	BK2_IO39	-	81N	NC	-	-
AG12	BK2_IO40	-	82P	NC	-	-
AH12	BK2_IO41	-	82N	NC	-	-
AK12	BK2_IO42	-	83P	BK2_IO22	-	53P
-	GND (Bank 2)	-	-	-	-	-

SELECT DEVICES DISCONTINUED

ispXPGA Logic Signal Connections: 900-Ball fpBGA (Cont.)

900 fpBGA Ball	LFX1200			LFX500		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
AJ18	BK3_IO14	-	100P	BK3_IO14	-	70P
-	-	-	-	GND (Bank 3)	-	-
AK18	BK3_IO15	-	100N	BK3_IO15	-	70N
AE18	BK3_IO16	-	101P	BK3_IO16	-	71P
AD18	BK3_IO17	-	101N	BK3_IO17	-	71N
AJ19	BK3_IO18	-	102P	BK3_IO18	-	72P
-	GND (Bank 3)	-	-	-	-	-
AK19	BK3_IO19	-	102N	BK3_IO19	-	72N
AH19	BK3_IO20	-	103P	NC	-	-
AG19	BK3_IO21	-	103N	NC	-	-
AK20	BK3_IO22	-	104P	NC	-	-
AJ20	BK3_IO23	-	104N	NC	-	-
AF19	BK3_IO24	-	105P	NC	-	-
AE19	BK3_IO25	-	105N	NC	-	-
AH20	BK3_IO26	-	106P	NC	-	-
-	GND (Bank 3)	-	-	-	-	-
AG20	BK3_IO27	-	106N	NC	-	-
AF20	BK3_IO28	-	107P	NC	-	-
AE20	BK3_IO29	-	107N	NC	-	-
AJ21	BK3_IO30	-	108P	NC	-	-
AK21	BK3_IO31	-	108N	NC	-	-
AG21	BK3_IO32	-	109P	NC	-	-
AF21	BK3_IO33	-	109N	NC	-	-
AK22	BK3_IO34	-	110P	NC	-	-
-	GND (Bank 3)	-	-	-	-	-
AJ22	BK3_IO35	-	110N	NC	-	-
AE21	BK3_IO36	-	111P	NC	-	-
AD21	BK3_IO37	-	111N	NC	-	-
AG22	BK3_IO38	-	112P	NC	-	-
AF22	BK3_IO39	-	112N	NC	-	-
AG23	BK3_IO40	-	113P	BK3_IO22	-	74P
-	-	-	-	GND (Bank 3)	-	-
AH23	BK3_IO41	-	113N	BK3_IO23	-	74N
AJ23	BK3_IO42	-	114P	BK3_IO24	-	75P
-	GND (Bank 3)	-	-	-	-	-
AK23	BK3_IO43	-	114N	BK3_IO25	-	75N
AF23	BK3_IO44	-	115P	BK3_IO26	-	76P
AE23	BK3_IO45	-	115N	BK3_IO27	-	76N
AJ24	BK3_IO46	-	116P	BK3_IO28	-	77P
AK24	BK3_IO47	-	116N	BK3_IO29	-	77N
AH24	BK3_IO48	-	117P	BK3_IO21	-	73N
AG24	BK3_IO49	VREF3	117N	BK3_IO20	VREF3	73P

SELECT DEVICES DISCONTINUED

Part Number Description

LFX XXXX X X – XX XXXXX X

Device Family
LFX

Gates
125 = 139K Gates
200 = 210K Gates
500 = 476K Gates
1200 = 1.25M Gates[1]

sysHSI Support
Blank = Supports sysHSI
E = No sysHSI Support

Power Supply Voltage
B = 2.5/3.3V
C = 1.8V

Grade
C = Commercial
I = Industrial

Package
F256 = 256-Ball fpBGA
FH516 = 516-Ball fpBGA (with Heat Spreader)
F516 = 516-Ball fpBGA (without Heat Spreader)
FE680 = 680-Ball fpSBGA
F900 = 900-Ball fpBGA
FN256 = Lead-Free 256-Ball fpBGA
FN900 = Lead-Free 900-Ball fpBGA[2]

Speed
5 = Fastest
4
3 = Slowest

1. Discontinued via PCN #03A-10.
2. Select products only. See Ordering Information tables below for specific support.

SELECT DEVICES DISCONTINUED

Ordering Information

Conventional Packaging

Commercial

Part Number	Gates	Voltage	Speed Grade	Package	Balls
LFX125B-05F256C	139K	2.5/3.3	-5	fpBGA	256
LFX125B-04F256C	139K	2.5/3.3	-4	fpBGA	256
LFX125B-03F256C	139K	2.5/3.3	-3	fpBGA	256
LFX125C-04F256C	139K	1.8	-4	fpBGA	256
LFX125C-03F256C	139K	1.8	-3	fpBGA	256
LFX125B-05F516C	139K	2.5/3.3	-5	fpBGA	516
LFX125B-04F516C	139K	2.5/3.3	-4	fpBGA	516
LFX125B-03F516C	139K	2.5/3.3	-3	fpBGA	516
LFX125C-04F516C	139K	1.8	-4	fpBGA	516
LFX125C-03F516C	139K	1.8	-3	fpBGA	516
LFX125B-05FH516C[1]	139K	2.5/3.3	-5	fpBGA	516
LFX125B-04FH516C[1]	139K	2.5/3.3	-4	fpBGA	516
LFX125B-03FH516C[1]	139K	2.5/3.3	-3	fpBGA	516
LFX125C-04FH516C[1]	139K	1.8	-4	fpBGA	516
LFX125C-03FH516C[1]	139K	1.8	-3	fpBGA	516
LFX200B-05F256C	210K	2.5/3.3	-5	fpBGA	256
LFX200B-04F256C	210K	2.5/3.3	-4	fpBGA	256
LFX200B-03F256C	210K	2.5/3.3	-3	fpBGA	256
LFX200C-04F256C	210K	1.8	-4	fpBGA	256
LFX200C-03F256C	210K	1.8	-3	fpBGA	256